STACKED DEVICE PACKAGE FOR PERIPHERAL AND CENTER DEVICE PAD LAYOUT DEVICE AND METHOD OF MAKING

ABSTRACT OF THE DISCLOSURE

An assembly method is disclosed that includes providing a substrate, securing a first semiconductor device on a first surface thereof, and superimposing at least a second semiconductor device at least partially over the first semiconductor device is disclosed. An outer peripheral portion of the second semiconductor device overhangs both the first semiconductor device and the substrate. Discrete conductive elements are placed between the outer peripheral portion of the second semiconductor device and a second surface of the substrate. Intermediate portions of the discrete conductive elements pass outside of a side surface of the substrate. Assemblies and packaged semiconductor devices that are formed in accordance with the method are also disclosed.

[FIG. 1A]